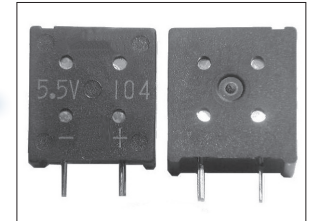


FEATURES

- DOUBLE LAYER CONSTRUCTION
- LONG DURATION POWER BACK-UP FOR CMOS RAM (UP TO 50 μ A DISCHARGE CURRENT)
- WIDE OPERATING TEMPERATURE (-40°C to +85°C)
- OPTIONAL TAPED PACKAGING FOR AUTOMATED INSERTION
- SUITABLE FOR FLOW SOLDERING
- UL94V-0 MOLDED CASE
- LEAD-FREE FINISH

RoHS Compliant
includes all homogeneous materials

*See Part Number System for Details



CHARACTERISTICS

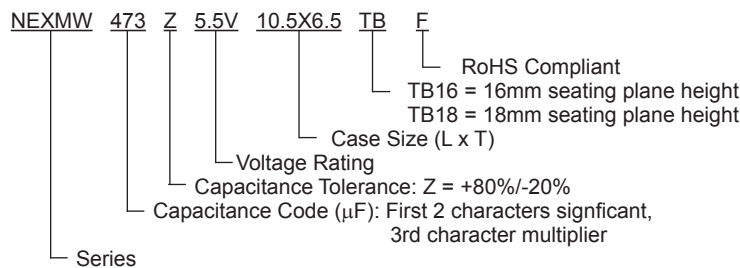
Rated Voltage Range	3.5 ~ 5.5VDC	
Rated Capacitance Range	0.047F ~ 0.47F (47,000 μ F ~ 470,000 μ F)	
Operating Temp. Range	-40°C ~ +85°C	
Capacitance Tolerance	+80%/-20% (Z)	
Load Life Test @ 85°C 1000 hours	Δ Capacitance Change	Less than $\pm$ 30% of initial measured value
	Maximum ESR	Less than 200% of the specified maximum value
	Current at 30 minutes	Less than 200% of the specified maximum value
Temperature Cycling (5 cycles, -40 ~ +85°C)	Δ Capacitance Change	Within +80%/-20% of specified value
	Maximum ESR	Less than specified maximum value
	Current at 30 minutes	Less than specified maximum value
Humidity Resistance (240 hours @ 40°C/90% RH)	Δ Capacitance Change	Less than $\pm$ 20% of initial measured value
	Maximum ESR	Less than 120% of the specified maximum value
	Current at 30 minutes	Less than 120% of the specified maximum value

Super Capacitor
Application Guide

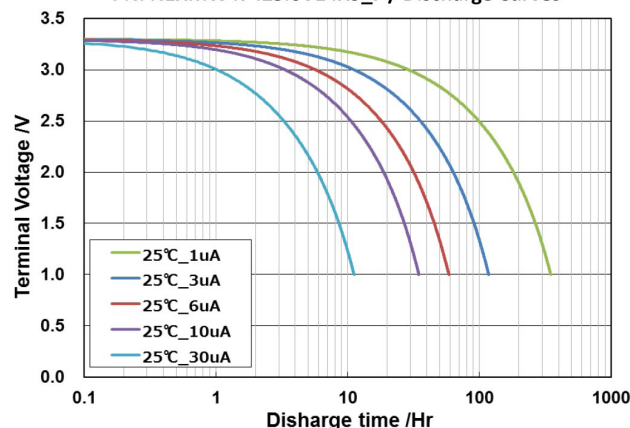
STANDARD VALUES AND SPECIFICATIONS

NIC P/N	Capacitance Value (F) Charge Discharge	Rated Voltage (VDC)	Max. Current @ 30 minutes (mA)	Max. ESR @ 1KHz (Ω)	Voltage Holding (V)
NEXMW104Z3.5V10.5X6.5TBF	0.100 -	3.5	0.090	50	-
NEXMW474Z3.6V14X9TBF	0.470 -	3.6	0.42	25	-
NEXMW473Z5.5V10.5X6.5TBF	0.047 0.062	5.5	0.071	200	4.2
NEXMW104Z5.5V10.5X6.5TBF	0.100 -	5.5	0.150	50	4.2

PART NUMBERING SYSTEM



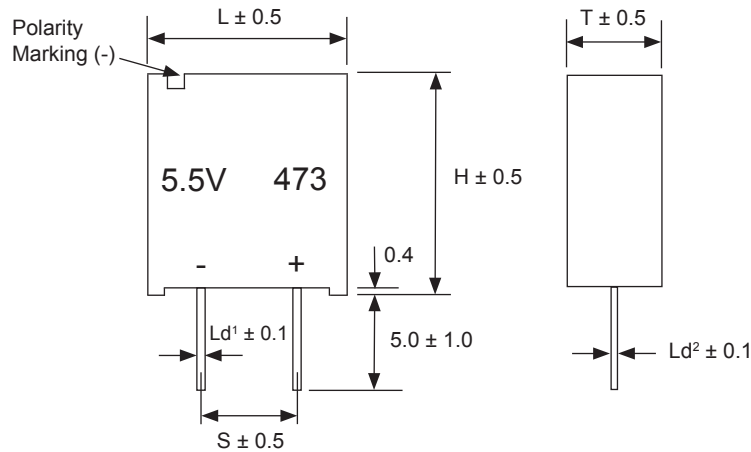
PN: NEXMW474Z3.6V14X9_F / Discharge Curves



CASE DIMENSIONS (mm)

NIC P/N	DIMENSIONS (mm)					
	L	H	S	T	Ld ¹	Ld ²
NEXMW104Z3.5V10.5X6.5TBF	10.5	11.5	5.0	6.5	0.5	0.4
NEXMW474Z3.6V14X9TBF	14.0	15.0	5.0	9.0	0.6	0.6
NEXMW473Z5.5V10.5X6.5TBF	10.5	11.5	5.0	6.5	0.5	0.4
NEXMW104Z5.5V10.5X6.5TBF	10.5	11.5	5.0	6.5	0.5	0.4

STANDARD BULK PACKAGING CONFIGURATION



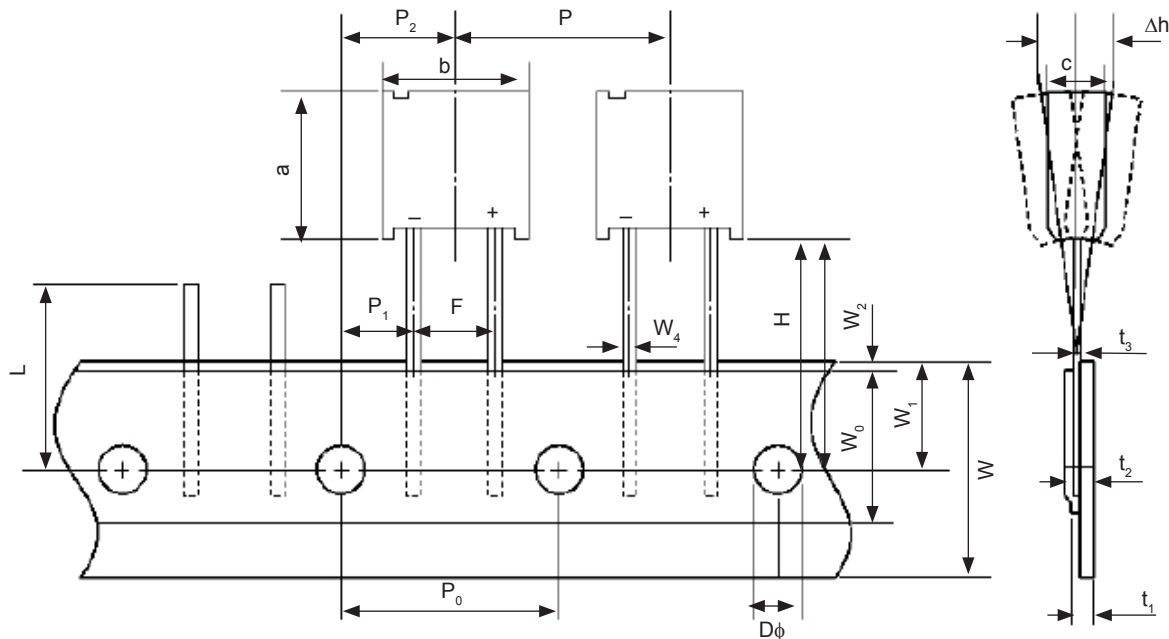
OPTIONAL LOW PROFILE, HORIZONTAL MOUNT



TAPING SPECIFICATIONS (mm)

a	b	c	W ₄	t ₃	P	P ₀	P ₁	P ₂	F	Δh	W	W ₀	W ₁	W ₂	H	D ₀	t ₁	t ₂	L
±0.5	±0.5	±0.5	±0.1	±0.1	±1.0	±0.3	±0.7	±1.3	±0.5	max.	+1/-0.5	min.	±0.5	max.	±0.5	±0.2	±0.2	max.	max.
11.5	10.5	6.5	0.5	0.4	12.7	12.7	3.85	6.35	5.0	2.0	18	12.5	9.0	3.0	16/18	φ4.0	0.7	1.5	11.0
15.0*	14.0*	9.0*	0.6*	0.6*	12.7	25.4*									18*		0.67*	1.7*	

*NEXMW474Z3.5V14X9TBF



PRECAUTIONS

Please review the notes on correct use, safety and precautions found at https://www.niccomp.com/resource/files/double/Double_Layer_Capacitor_Guide_0810-RevBrA7.pdf. If in doubt or uncertainty, please review your specific application - process details with NIC's technical support personnel: tpmg@niccomp.com

